

MediaTek readies for the 5G era (and to take on the likes of Qualcomm) with the launch of the Dimensity 1000-- a high-end SoC featuring an integrated 5G modem, together with the latest in Arm CPU cores.



First announced back in May 2019 as simply the "5G SoC", the Dimensity 1000 represents a rebrand ushering "the 5th dimension" in mobile connectivity. It promises the fastest throughput yet, at 4.7Gbps downlink and 2.5Gbps uplink speeds over sub-6GHz networks, and supports standalone and non-standalone (SA/NSA) sub-6GHz networks, as well as multi-node support for every cellular connectivity generation from 2G to 5G. Wireless connectivity also includes Wifi 6 and Bluetooth 5.1+, with 1Gbps throughput in both downlink and uplink speeds.

In addition, the Dimensity 1000 carries x4 Arm Cortex-A77 cores operating at 2.4GHz and x4 Cortex-A55 cores running at 2GHz, plus a Mali-G77 GPU for seamless streaming and gaming. A MediaTek APU 3.0 claims to double performance over the previous generation to 4.5 TOPS. The APU handles AI-camera enhancements for autofocus, auto exposure, auto white balance, noise reduction, HDR and face detection, and a 5-core image signal processor supports 80MP camera sensors shooting video at 24fps and multi-camera options such as 32+16MP dual cameras.

"Our Dimensity series is a culmination of MediaTek's investment in 5G and positions us as a leader driving 5G development and innovation. Our 5G technology goes head-to-head with anyone in the industry," the company says. "We chose the name Dimensity to highlight how our 5G solutions are driving new waves of innovation and experiences, much like the fabled fifth dimension. Our first announced chip, MediaTek Dimensity 1000, gives consumers a significantly faster, more intelligent and all-around incredible mobile experience."

The first products packing the Dimensity 1000 chip should hit the market on Q1 2020.

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